

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yamauchi, M.

Serial No.: 09/733,036

Group Art Unit: 2828

Filed: December 11, 2000

Examiner: Leung, Q.

For: SEMICONDUCTOR LASER DIODE CHIP AND ITS POSITIONING AND MOUNTING METHOD

Honorable Assistant Commissioner of Patents
Washington, D.C. 20231AMENDMENT UNDER 37 C.F.R. §1.111

Sir:

In response to the Office Action dated January 17, 2001, please amend the above-identified application as follows:

IN THE CLAIMS:

Please add the following new claims:

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1 21. A semiconductor laser diode chip with an active layer mounted on a substrate,
2 comprising:
3 a first pair of marks formed in the vicinity of said active layer and straddling said
4 active layer; and
5 a second pair of marks straddling said active layer, said second pair of marks located
6 at a further distance from said active layer than said first pair of marks,
7 wherein said second pair of marks align with a pair of substrate side marks formed at
8 a position opposed to said second pair of marks.

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1 22. The semiconductor laser diode chip, as claimed in claim 21, wherein said first pair of
2 marks comprises thin lines formed parallel to said active layer.

1 23. The semiconductor laser diode chip, as claimed in claim 22, wherein said first pair of
2 marks are formed by a metallic film.